

Discription

The HSP4022-01FTG-C protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.

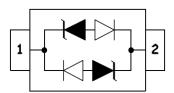
Features

- ★ Transient protection for high-speed data lines IEC 61000-4-2(ESD) ±30kV (Contact) ±30kV (Air)
- IEC 61000-4-4(EFT) 40A (5/50 ns) ★ Peak power dissipation: 350W (8/20us)
- ★ Working voltages : 12V
- Protects one Vcc or data line
- ★ Low clamping voltage
- ★ Low leakage current

Orderingin formation







Circuit Diagram

Product ID	Pack	Qty(PCS)
HSP4022-01FTG-C	SOD-323	3000

Absolute Ratings(Tamb = 25°C)

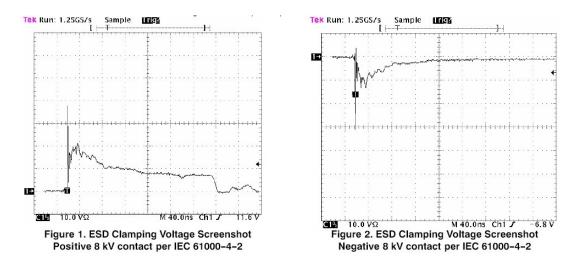
Symbol	Parameter	Value	Units	
P _{PP}	Peak Pulse Power ($t_p = 8/20 \mu s$)	350	W	
TL	Maximum lead temperature for soldering during 10s	260	°C	
T _{stg}	Storage Temperature Range	-55 to +155	°C	
T _{op}	Operating Temperature Range	-40 to +125	°C	
Tj	Maximum junction temperature	150	°C	
	IEC61000-4-2 (ESD) air disch contact disch		±30 ±30	KV
	IEC61000-4-4 (EFT)		40	А



Electrical Characteristics

Symbol	Parameter	Test Condition	Min	Тур	Max	Units
Vrwm	Reverse Working Voltage				12	V
Vbr	Reverse Breakdown Voltage	I⊤ = 1mA	13.3			V
IR	Reverse Leakage Current	$V_{\text{RWM}} = 12V$			1	μA
Vc	Clamping Voltage	I _{RWM} = 1A, t _P = 8/20µs			19	V
		I _{RWM} = 12A, t _p = 8/20μs			28.6	V
С	Junction Capacitance	$V_R = 0V, f = 1MHz$		1.0	1.2	pF

Typical Characteristics





Outline And Dimensions

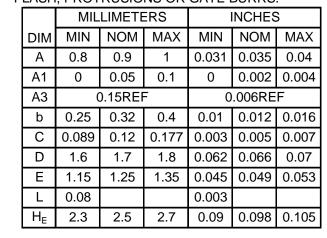
Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

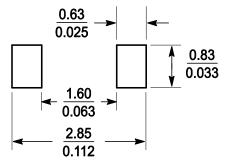
2. CONTROLLING DIMENSION: MILLIMETERS.

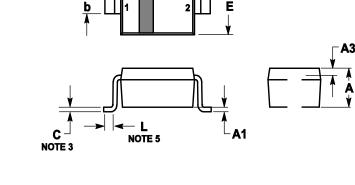
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



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